

KBU8005~KBU810

Rev.C Feb.-2015

描述 / Descriptions

整流桥，反向电压：50V~1000V，正向电流：8.0A，KBU封装。
Silicon Bridge Rectifiers, Reverse Voltage:50to1000V,Forward Current:8.0A,KBU package.

特征 / Features

浪涌额定过载电流 155A，塑料材料阻燃等级 UL94-V0。
Surge overload rating -155 amperes peak,Plastic material has UL94-V0.

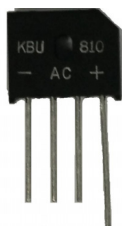
用途 / Applications

一般用途。
General purpose.

内部等效电路图 / Equivalent Circuit

见引脚排列图/ See Pinning.

引脚排列 / Pinning



印章代码 / Marking

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

| 参数 Parameter | 符号 Symbol | 数值 Rating | | | | | | | 单位 Unit |
|--|--------------|--------------|--------|--------|--------|--------|--------|--------|------------|
| | | KBU8005 | KBU801 | KBU802 | KBU804 | KBU806 | KBU808 | KBU810 | |
| Maximum Recurrent Peak Reverse Voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Output Current at $T_C=100^\circ\text{C}$ | $I_{(AV)}$ | 8.0 | | | | | | | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Method) | I_{FSM} | 155 | | | | | | | A |
| Typical Junction Capacitance Per Element (Note1) | C_j | 250 | | | | | | | pF |
| Operating Temperature Range | T_j | -55~150 | | | | | | | °C |
| Storage Temperature Range | T_{stg} | -55~150 | | | | | | | °C |

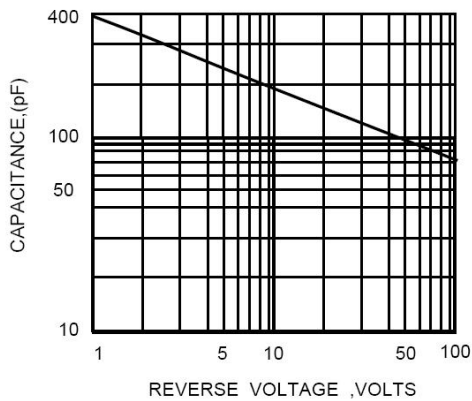
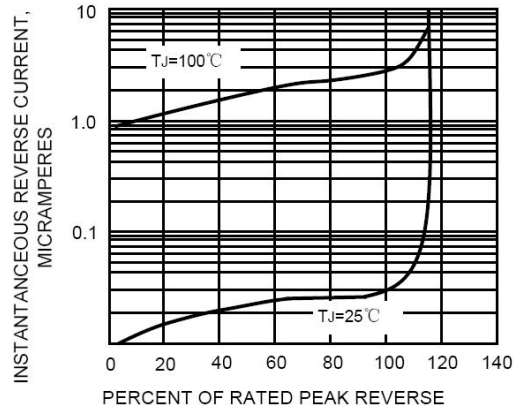
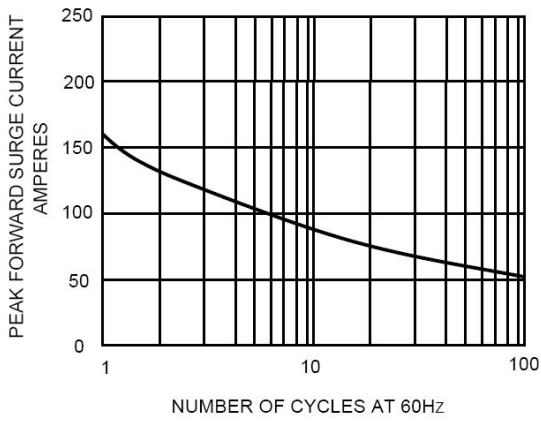
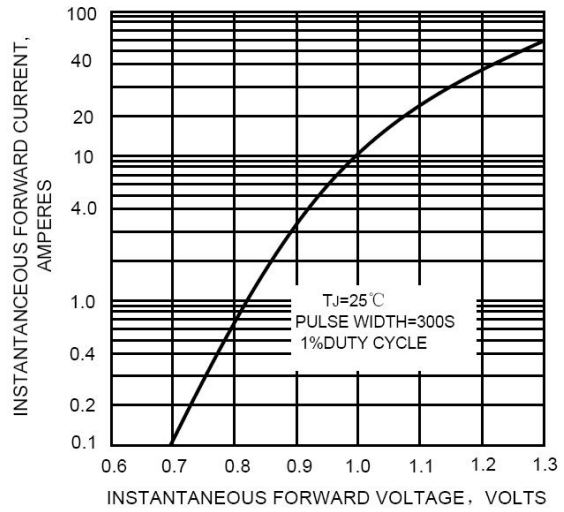
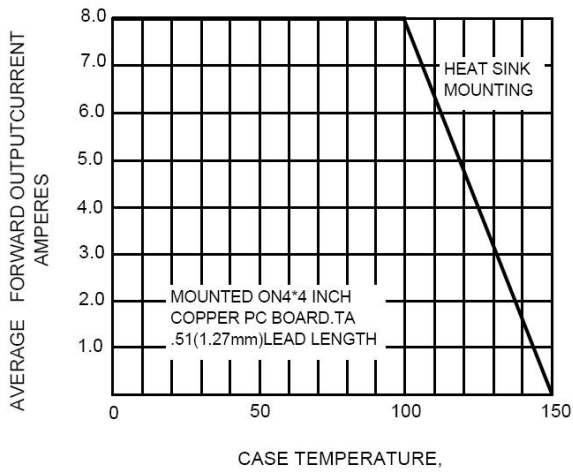
Note:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

电性能参数 / Electrical Characteristics(Ta=25°C)

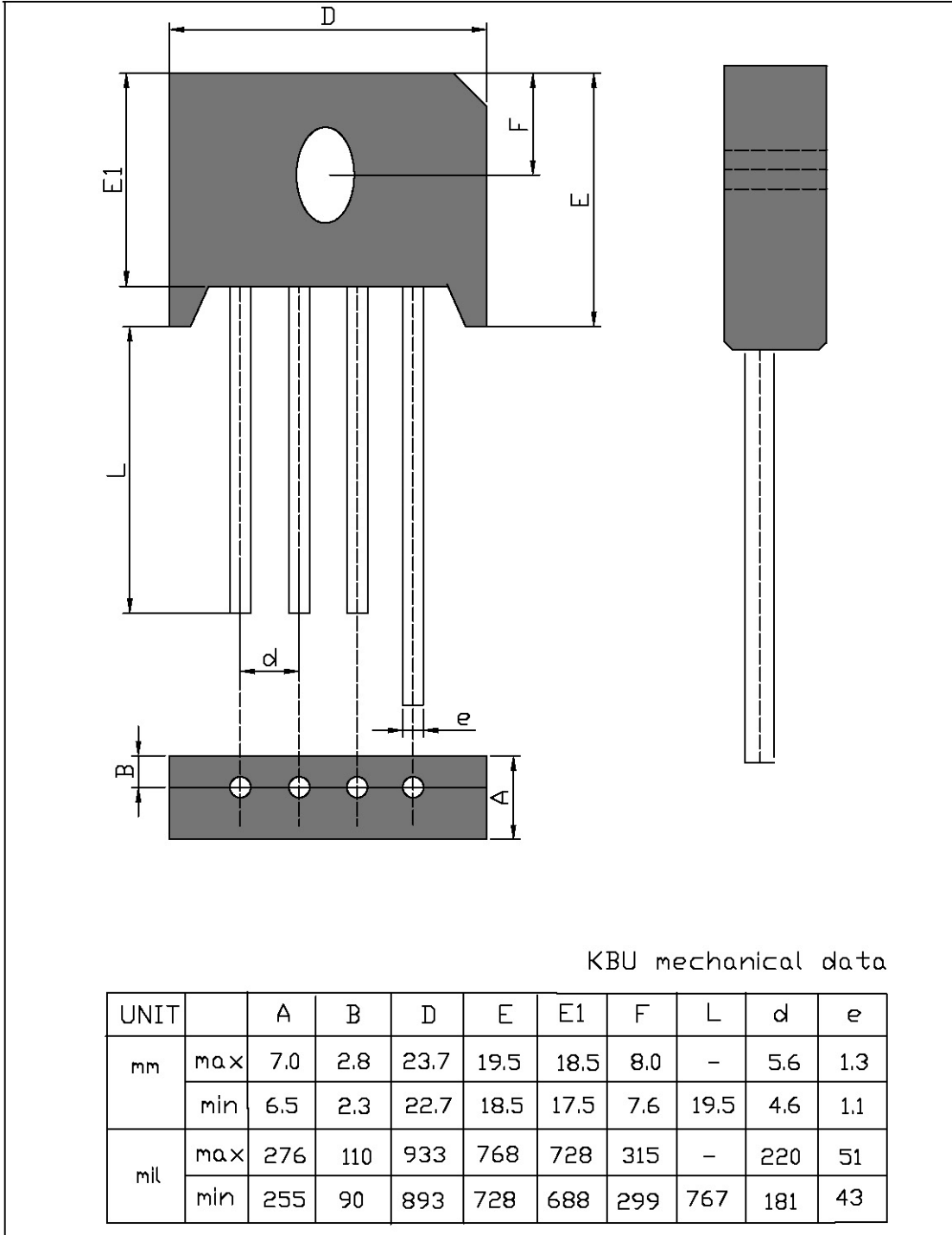
| 参数 Parameter | 符号 Symbol | 测试条件 Test Conditions | 数值 Rating | 单位 Unit |
|---|--------------|-------------------------|--------------|---------------|
| Maximum Instantaneous Forward Voltage Drop per Element | V_F | $I_F=4.0\text{A}$ | 1.0 | V |
| Maximum DC Reverse Current at Maximum DC Blocking Voltage | I_R | $T_J=25^\circ\text{C}$ | 10 | μA |
| | | $T_J=100^\circ\text{C}$ | 300 | μA |

电参数曲线图 / Electrical Characteristic Curve

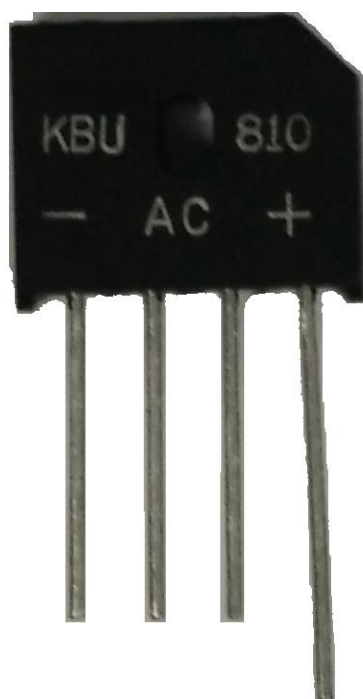


外形尺寸图 / Package Dimensions

KUB



印章说明 / Marking Instructions



说明：

KBU810：产品型号

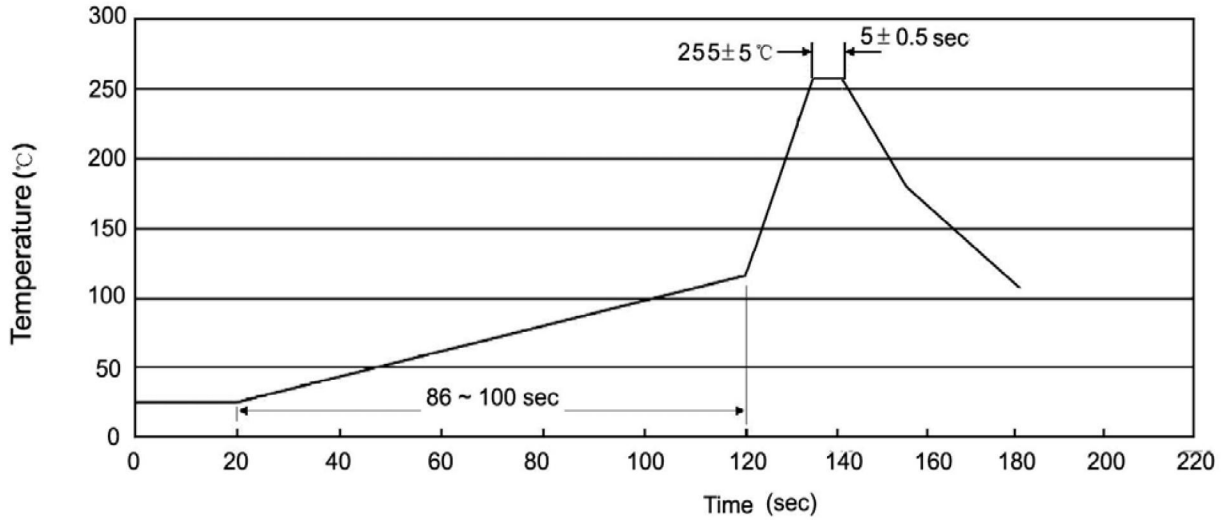
- AC +：引脚功能

Note:

KBU810：Product Type

- AC +：Pin function

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

盒装包装 / BOXED

| Package Type 封装形式 | Units 包装数量 | | | Dimension 包装尺寸 (unit: mm ³) | | |
|----------------------|------------------------|------------------------------|------------------------|---|-------------|-------------|
| | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | | Inner Box 盒 | Outer Box 箱 |
| KBU | 400 | 6 | 2400 | | 230×230×49 | 490×240×180 |

使用说明 / Notices